ABSTRACT

A heat sink for integrated circuits is limited substantially to heat transfer fins on one or more heat pipe tubes, the tube(s) functioning as a base for the heat sink. The heat pipe tube has a flattened oval cross-section and can snap-fit in openings through the fins. The tube is exposed on one side of the heat sink for contact with the heat generating circuit. The fins can be flat or irregular and can have a collar engaging the heat pipe tube. In one example, the heat pipe runs perpendicular to vertical fins along the bottom of a standing fin stack. In another embodiment two U-shaped heat pipe tubes carry a layered stack, the bottom of the U-shapes being presented under the lowermost in the stack. A clamp urges the heat sink against the heat source.

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